L Number	Hits	Search Text	DB	Time stamp
1	1	, , , , , , , , , , , , , , , , , , , ,	USPAT	2002/06/30 00:11
2	1		USPAT	2002/06/30 00:11
3	2	(	USPAT	2002/06/30 01:12
4	30128		USPAT;	2002/06/30 01:13
		(bump or ball)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
5	20040		IBM_TDB	
] 3	28848	(device and (post or column or pillar) and	USPAT;	2002/06/30 02:19
		(bump or ball)) and (@ad<20010427)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
6	4679	((device and (post or column or pillar)	IBM_TDB USPAT;	2000/06/20 01 15
		and (bump or ball)) and (@ad<20010427))	US-PGPUB;	2002/06/30 01:15
		and pad	EPO; JPO;	
			DERWENT;	
	ļ		IBM TDB	
7	566		USPAT;	2002/06/30 01:30
ĺ		and (bump or ball)) and (@ad<20010427))	US-PGPUB;	
		and (pad with (post or column or pillar))	EPO; JPO;	
†			DERWENT;	
	1	/# C1 01 4 0 0 H) - Tre	IBM_TDB	
8	1	("6191493").PN.	USPAT	2002/06/30 01:59
10	1 19	6191493.URPN. ("4472730"   "5093281"   "5128746"	USPAT	2002/06/30 01:46
10	19		USPAT	2002/06/30 01:47
		"5139969"   "5171716"   "5205036"     "5237013"   "5244838"   "5304460"		
		"5304512"   "5321303"   "5331235"		
		"5371044"   "5373190"   "5427938"		
		"5438478"   "5474958"   "6007357"		
		"6014318").PN.		
11	1154	257/786.ccls.	USPAT;	2002/06/30 02:00
			US-PGPUB;	=::=, ::, :: :::::::::::::::::::::::::
			EPO; JPO;	
			DERWENT;	
12	1007	057/706	IBM_TDB	
12	1087	257/786.ccls. and (@ad<20010427)	USPAT;	2002/06/30 02:09
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	İ
13	1045	257/786.ccls. and (@ad<20000427)	USPAT;	2002/06/30 02:01
		(000 2000121)	US-PGPUB;	2002/00/30 02:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	48	(257/786.ccls. and (@ad<20010427)) and	USPĀT;	2002/06/30 02:10
	ļ	ball and (pillar or column or post)	US-PGPUB;	
			EPO; JPO;	
	ĺ		DERWENT;	
15	372	257/620.ccls. and (@ad<20010427)	IBM_TDB	2000/06/22 22 52
10	312	2377020.CC15. and (@ad<20010427)	USPAT;	2002/06/30 02:09
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	7	(257/620.ccls. and (@ad<20010427)) and	USPAT;	2002/06/30 02:52
1	1	ball and (pillar or column or post)	US-PGPUB;	,,
		-	EPO; JPO;	
			DERWENT;	
-			IBM_TDB	
17	8	438/462.ccls. and ball and (pillar or	USPAT;	2002/06/30 02:16
		column or post)	US-PGPUB;	
[	l		EPO; JPO;	
]			DERWENT; IBM TDB	
L			לחד ויוחד	

18			_	
18	11	438/460.ccls. and ball and (pillar or column or pos <del>t</del> )	USPAT; US-PGPUB;	2002/06/30 02:16
			EPO; JPO;	
			DERWENT; IBM TDB	
19	21		USPAT;	2002/06/30 02:18
ŀ		column or post)	US-PGPUB;	200,00,00 02.10
			EPO; JPO;	
			DERWENT; IBM TDB	
20	852	T ( COMPANY OF WEARTS) WITH I DAM OF LIGHT OF	USPAT;	2002/06/30 02:19
		electrode)) and ball and (pillar or column or post)	US-PGPUB;	
21		Outding Of post;	EPO; JPO; DERWENT;	
	707		IBM TDB	
21	797	(((center or middle) with (pad or trace or electrode)) and ball and (pillar or	USPĀT;	2002/06/30 02:53
		column or post)) and (@ad<20010427)	US-PGPUB; EPO; JPO;	
İ		(0.00.000012),	DERWENT;	
22	628	////gonton on middle)	IBM_TDB	
	020	((((center or middle) with (pad or trace or electrode)) and ball and (pillar or	USPAT; US-PGPUB;	2002/06/30 02:53
		column or post)) and (@ad<20010427)) and	EPO; JPO;	
		(device or chip or wafer)	DERWENT;	
23	1	("6191493").PN.	IBM_TDB USPAT	0000/05/00 00
24	32051	(step or stepped) with (molding or mold or	USPAT;	2002/06/30 02:51 2002/06/30 02:52
		encapsulant or rein)	US-PGPUB;	2002/00/30 02.32
			EPO; JPO; DERWENT;	
	1		IBM TDB	
25	811	((step or stepped) with (molding or mold	USPAT;	2002/06/30 02:53
		or encapsulant or rein)) and ball and (pillar or column or post)	US-PGPUB; EPO; JPO;	
		pose,	DERWENT;	
26	766	///atan an atana N	IBM_TDB	
20	766	(((step or stepped) with (molding or mold or encapsulant or rein)) and ball and	USPAT; US-PGPUB;	2002/06/30 02:53
		(pillar or column or post)) and	EPO; JPO;	
		(@ad<20010427)	DERWENT;	
27	494	((((step or stepped) with (molding or mold	IBM_TDB USPAT;	2002/06/20 02 05
		or encapsulant or rein)) and ball and	US-PGPUB;	2002/06/30 03:05
		(pillar or column or post)) and	EPO; JPO;	
		(@ad<20010427)) and (device or chip or wafer)	DERWENT;	,
28	2306	(dielectric or insulating or insulation)	IBM_TDB USPAT;	2002/06/30 03:06
		near polyimide	US-PGPUB;	
	1		EPO; JPO; DERWENT;	
			IBM TDB	
29	382	((dielectric or insulating or insulation)	USPĀT;	2002/06/30 03:07
	1	near polyimide) and 257/\$.ccls.	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	

Search History 6/30/02 3:07:45 AM Page 2 c:\apps\east\bin\\default.wsp

L Number	Hits	Search Text	DB	Time stamp
1	899	257/787.ccls	USPAT	2002/06/30 13:43
2	810	257/787.ccls. and (@ad<20000423)	USPAT	2002/06/30 14:22
3	0	(stepped adj shape) near encapsulant	USPAT	2002/06/30 14:10
4	0	(stepped adj shape) with encapsulant	USPAT	2002/06/30 14:09
5	2	(stepped adj shape) near (encapsulant or	USPAT;	2002/06/30 14:13
		mold)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	0	(stepped adj shape) with encapsulant	USPAT;	2002/06/30 14:16
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	1	("6351030").PN.	USPAT	2002/06/30 14:21
8	45	(remove or cut) near encapsulant	USPAT;	2002/06/30 14:25
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	36	((remove or cut) near encapsulant) and	USPAT	2002/06/30 14:26
		(@ad<20000428)		
10	273	(remove or cut) with (encapsulant or	USPAT;	2002/06/30 14:25
1		(moldong adj resin))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	192	((remove or cut) with (encapsulant or	USPAT	2002/06/30 14:26
		(moldong adj resin))) and (@ad<20000428)	1	1